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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/621,611	07/18/2003	Yoichi Momose	116623	2899
25944	7590 12/14/2004		EXAMINER	
OLIFF & B	ERRIDGE, PLC	KIM, RIC	KIM, RICHARD H	
P.O. BOX 19	928 JIA, VA 22320	ART UNIT	PAPER NUMBER	
ALEXANDR	IIA, VA 22320		2871	
			DATE MAILED: 12/14/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)			
	10/621,611	MOMOSE, YOICHI			
Office Action Summary	Examiner	Art Unit			
	Richard H Kim	2871			
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply					
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.  - If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.  - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).					
Status					
Responsive to communication(s) filed on  2a) ☐ This action is FINAL. 2b) ☑ This  3) ☐ Since this application is in condition for allowar closed in accordance with the practice under E	action is non-final. nce except for formal matters, pro				
Disposition of Claims					
4) ☐ Claim(s) 1-10 is/are pending in the application. 4a) Of the above claim(s) is/are withdray 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-10 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	vn from consideration.				
Application Papers					
9) The specification is objected to by the Examiner 10) The drawing(s) filed on 03 November 2003 is/an Applicant may not request that any objection to the of Replacement drawing sheet(s) including the correction 11) The oath or declaration is objected to by the Ex	re: a) $\square$ accepted or b) $\square$ objected are discountly accepted in abeyance. See on is required if the drawing(s) is obj	e 37 CFR 1.85(a). ected to. See 37 CFR 1.121(d).			
Priority under 35 U.S.C. § 119					
<ul> <li>12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents have been received.</li> <li>2. Certified copies of the priority documents have been received in Application No.</li> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>					
Attachment(s)  1) Notice of References Cited (PTO-892)  2) Notice of Draftsperson's Patent Drawing Review (PTO-948)  3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal Pa				

Application/Control Number: 10/621,611

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## **DETAILED ACTION**

## Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamada et al. (US 6,013,339).

Referring to claims 1, 6, 7 and 10, Yamada et al. discloses an electronic device comprising a pair of substrates (Fig. 5, ref. 12a, 12b); a liquid crystal layer provided between the pair of substrates (13); and a sealing material bonding the pair of substrates to each other and enclosing the liquid crystal layer between the pair of substrate (3); the sealing material containing a photocurable component and a thermosetting component (col. 10, lines 25-27), the photocurable component having a curing rate in the range of from 60% to 95% (col. 16, lines 2-3), and the thermosetting component having a curing rate in the rage of from 60%-90% (col. 16, lines 5-6). Yamada et al. further discloses a method of manufacturing comprising applying an adhesive onto at least one of surface of the pair of substrates to form a closed shape in a region of the surface thereof (Fig. 8, ref. 3); disposing spacers on at least one of the surfaces of the pair of substrates (2); dripping liquid crystal onto at least one of the surfaces of the pair of substrates after the adhesive and spacers are disposed (13), bonding the pair of substrate to each other after the liquid crystal is dripped (col. 19, lines 19-23); and curing the adhesive after the bonding is formed, the adhesive being an uncured material which is formed to a sealing material by curing

(col. 16, lines 10-15). Furthermore, Yamada et al. discloses the device wherein the liquid crystal is injected through a liquid crystal inlet (Fig. 2, ref. 9). However, the reference does not disclose that the *maximum* curing rate is in the rate of from 60% - 95%.

It would have been obvious to one having ordinary skill in the art at the time the invention was made for the maximum curing rate to be from 60% - 90% since Yamada et al. discloses that the proper curing rate prevents the generation of defect goods in production due to alignment dislocation, and therefore improves production efficiency. Therefore, an artisan having ordinary skill in the art would have known to determine the optimum curing rate of the respective material in order to achieve excellent production efficiency (col. 16, lines 1-15).

Referring to claims 2 and 3, Yamada et al. discloses a device wherein the sealing material includes a resin containing the photocurable component, a resin containing the photocurable component, a resin containing the thermosetting component, and a resin containing the photocurable component and the thermosetting component is the same molecular chain (col. 16, lines 28-67; col. 17, lines 1-10).

Referring to claim 4, Yamada et al. discloses the device wherein the photocurable component includes at least one of an acrylic group and a methacrylic group (col. 16, lines 28-37).

Referring to claim 5, Yamada et al. discloses that the thermosetting component includes an epoxy group (col. 4, lines 39-40).

Referring to claim 8, Yamada et al. discloses the method previously recited. Yamada et al. further discloses that the curing of the adhesive includes a light irradiation substep of curing

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the photocurable component (col. 16, lines 10-12), and the amount of light irradiation is 1000 to 6000 mJ/cm<sup>2</sup> (co. 17, lines 35-36).

Referring to claim 9, Yamada et al. disclose the method previously recited, and further discloses that the curing of the adhesive includes a heating substep of curing the thermosetting component. However, the reference does not disclose that the heating temperature and the heating time in the heating substep being set to 60 to 160 degrees Celsius and 20 to 300 minutes, respectively.

It would have been obvious to one having ordinary skill in the art at the time the invention was made for the heating time in the heating substep being to be set to 60 to 160 degrees Celsius and 20 to 300 minutes, respectively since the time and temperature in which to efficiently cure the adhesive is a result effective variable. Determining the optimum time and temperature to cure the adhesive would result in efficient curing.

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Richard H Kim whose telephone number is (571)272-2294. The examiner can normally be reached on 9:00-6:30 M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Robert H Kim can be reached on (571)272-2293. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Richard H Kim Examiner Art Unit 2871

**RHK** 

TARIFUR R. CHOWDHURY
PRIMARY EXAMINER